PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MAX3243ECDB	Obsolete	Production	SSOP (DB) | 28	-	-	Call TI	Call TI	0 to 70	MAX3243EC
MAX3243ECDBR	Active	Production	SSOP (DB) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243EC
MAX3243ECDBR.A	Active	Production	SSOP (DB) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243EC
MAX3243ECDW	Obsolete	Production	SOIC (DW) | 28	-	-	Call TI	Call TI	0 to 70	MAX3243EC
MAX3243ECDWR	Active	Production	SOIC (DW) | 28	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243EC
MAX3243ECDWR.A	Active	Production	SOIC (DW) | 28	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MAX3243EC
MAX3243ECPW	Obsolete	Production	TSSOP (PW) | 28	-	-	Call TI	Call TI	0 to 70	MP243EC
MAX3243ECPWR	Active	Production	TSSOP (PW) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MP243EC
MAX3243ECPWR.A	Active	Production	TSSOP (PW) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MP243EC
MAX3243ECPWRG4	Active	Production	TSSOP (PW) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	MP243EC
MAX3243ECRHBR	Active	Production	VQFN (RHB) | 32	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	MP243E
MAX3243ECRHBR.A	Active	Production	VQFN (RHB) | 32	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	MP243E
MAX3243ECRHBRG4	Active	Production	VQFN (RHB) | 32	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	MP243E
MAX3243ECRHBRG4.A	Active	Production	VQFN (RHB) | 32	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	MP243E
MAX3243EIDB	Obsolete	Production	SSOP (DB) | 28	-	-	Call TI	Call TI	-40 to 85	MAX3243EI
MAX3243EIDBR	Active	Production	SSOP (DB) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243EI
MAX3243EIDBR.A	Active	Production	SSOP (DB) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243EI
MAX3243EIDBRG4	Active	Production	SSOP (DB) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243EI
MAX3243EIDBRG4.A	Active	Production	SSOP (DB) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243EI
MAX3243EIDW	Obsolete	Production	SOIC (DW) | 28	-	-	Call TI	Call TI	-40 to 85	MAX3243EI
MAX3243EIDWR	Active	Production	SOIC (DW) | 28	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243EI
MAX3243EIDWR.A	Active	Production	SOIC (DW) | 28	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243EI
MAX3243EIDWRG4	Active	Production	SOIC (DW) | 28	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX3243EI
MAX3243EIPW	Obsolete	Production	TSSOP (PW) | 28	-	-	Call TI	Call TI	-40 to 85	MP243EI
MAX3243EIPWR	Active	Production	TSSOP (PW) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP243EI
MAX3243EIPWR.A	Active	Production	TSSOP (PW) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP243EI
MAX3243EIPWRE4	Active	Production	TSSOP (PW) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP243EI
MAX3243EIPWRG4	Active	Production	TSSOP (PW) | 28	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MP243EI
MAX3243EIRHBR	Active	Production	VQFN (RHB) | 32	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	MR243E

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MAX3243EIRHBR.A	Active	Production	VQFN (RHB) | 32	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	MR243E
MAX3243EIRHBRG4	Active	Production	VQFN (RHB) | 32	3000 | LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	MR243E

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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